

# MECHANICAL CASE OUTLINE

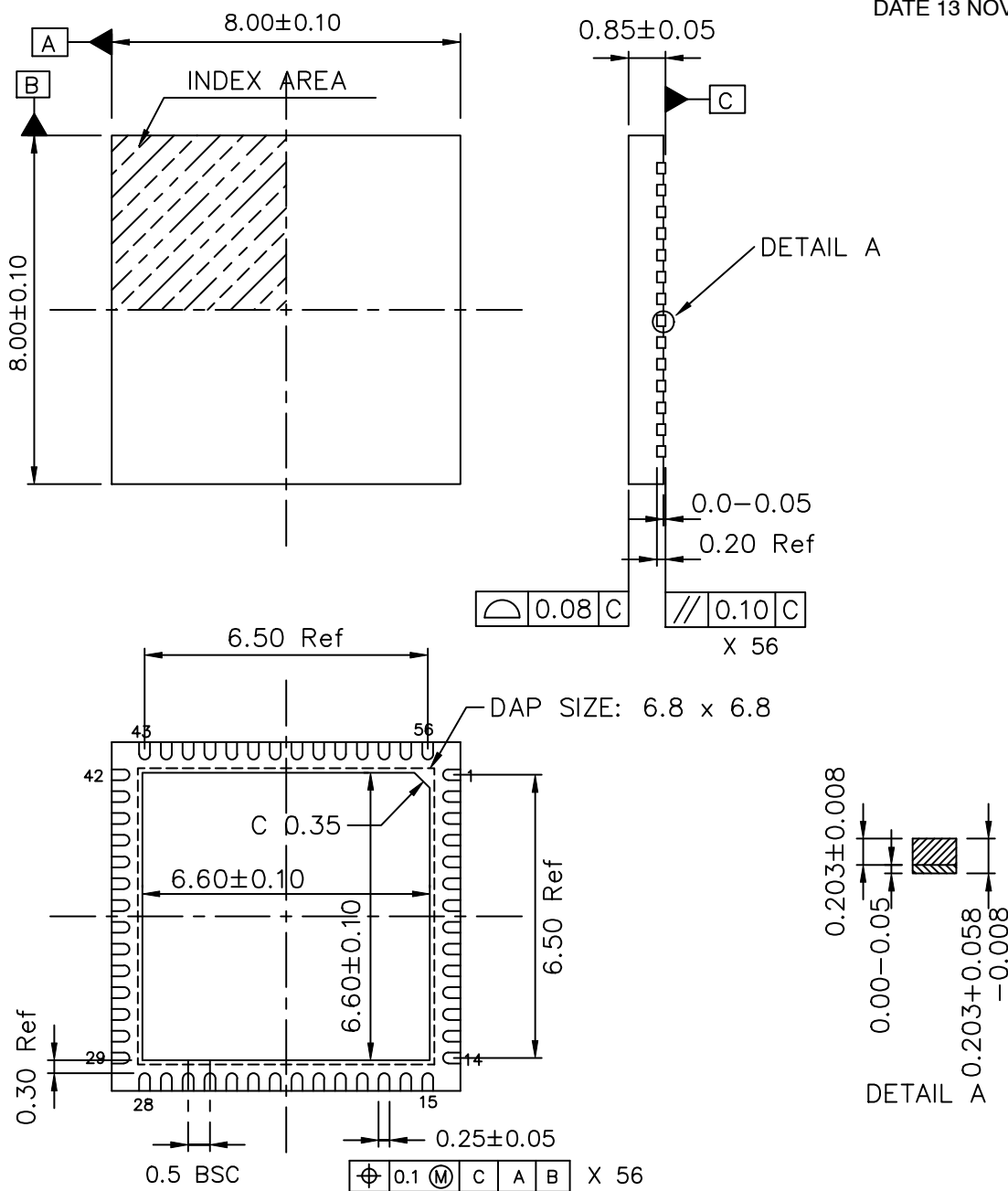
## PACKAGE DIMENSIONS

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ON

QFN56 8x8  
CASE 485EQ  
ISSUE A

DATE 13 NOV 2015



### NOTES:

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS. COPLANARITY SHALL NOT EXCEED 0.08 mm.
3. WARPAGE SHALL NOT EXCEED 0.10 mm.
4. PACKAGE LENGTH / PACKAGE WIDTH ARE CONSIDERED AS SPECIAL CHARACTERISTIC(S).
5. REFER JEDEC MO-220.

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